

STH180N10F3-6

N-channel 100 V, 3.9 mΩ typ.,180 A, STripFET™ F3 Power MOSFET in H²PAK-6 package

Datasheet - production data

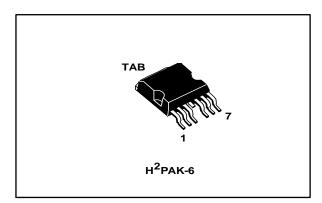
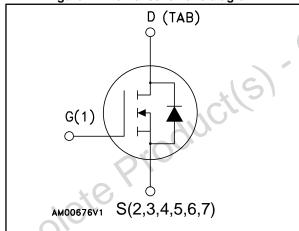


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	<u>-</u>
STH180N10F3-6	100 V	4.5 mΩ	180 A

- Low on-resistence R_{DS(on)}
- 100% avalanche tested

Applications

Switching applications

Description

This device is an N-channel Power MOSFET developed using STripFET™ F3 technology. It is designed to minimize on-resistance and gate charge to provide superior switching performance.

Table 1: Device summary

Order code	Marking	Package	Packing
STH180N10F3-6	180N10F3	H ² PAK-6	Tape and reel

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STH180N10F3-6 Electrical ratings

Electrical ratings 1

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit			
V _{DS}	Drain-source voltage	100	V			
V _{GS}	Gate-source voltage	± 20	V			
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	180	А			
I _D ⁽¹⁾	Drain current (continuous) at T _C = 100 °C	120	А			
I _{DM} ⁽²⁾	Drain current (pulsed)	720	А			
Б	Total dissipation at T _C = 25 °C	315	W			
Ртот	Derating factor	2.1	W/°C			
dv/dt	Peak diode recovery voltage slope	20	V/ns			
E _{AS} ⁽³⁾	Single pulse avalanche energy	350	mJ			
TJ	Operating junction temperature	-55 to 175	°C			
T_{stg}	Storage temperature	-55 to 175	°C			
Notes: (1) Current limited by package (2) Pulse width limited by safe operating area (3) Starting T _J = 25 °C, I _D = 80, V _{DD} = 50 V						

Notes:

Table 3: Thermal resistance

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	0.48	°C/W
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-pcb	35	°C/W

Notes:

⁽¹⁾Current limited by package

⁽²⁾Pulse width limited by safe operating area

 $^{^{(3)}}Starting~T_J = 25~^{\circ}C,~I_D = 80,~V_{DD} = 50~V$

Josolete Josolete $\ensuremath{^{(1)}}\xspace$ When mounted on FR-4 board of 1 inch², 2 oz Cu

Electrical characteristics STH180N10F3-6

Electrical characteristics 2

(T_{CASE} = 25 °C unless otherwise specified)

Table 4: On/off-state

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage (V _{GS} = 0)	I _D = 250 μA	100			V
I _{DSS}	Zana mata walta na duain	V _{DS} = 100 V			10	μΑ
	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = 100 V; T _C = 125 °C			100	μΑ
I _{GSS}	Gate body leakage current (V _{DS} = 0)	V _{GS} = ±20 V			±200	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V
R _{DS(on)}	Static drain-source on- resistance	$V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}$.0	3.9	4.5	mΩ

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance			6665		pF
C _{oss}	Output capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$		786		pF
C _{rss}	Reverse transfer capacitance	$V_{GS} = 0$	_	49		pF
Q_g	Total gate charge	$V_{DD} = 50 \text{ V}, I_D = 120 \text{ A}$		114.6		nC
Q_gs	Gate-source charge	V _{GS} = 10 V		38.8		nC
Q_gd	Gate-drain charge	See Figure 14: "Gate charge test circuit"		31.9		nC

Table 6: Switching times

	Table 6: Switching times						
	Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
10	t _{d(on)}	Turn-on delay time	$V_{DD} = 50 \text{ V}, I_D = 60 \text{ A},$		25.6		ns
	t _r	Rise time	$R_G = 4.7 \Omega, V_{GS} = 10 V$	- ⊢	97.1		ns
	t _{d(off)}	Turn-off delay time	See Figure 13: "Switching times test		99.9	-	ns
	t _f	Fall time	circuit for resistive load"		6.9		ns

Table 7: Source-drain diode

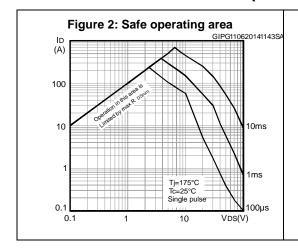
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current				180	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)				720	Α
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 120 \text{ A}, V_{GS} = 0$			1.5	V
t _{rr}	Reverse recovery time	I _{SD} = 120 A,	-	83.4		ns
Q_{rr}	Reverse recovery charge	di/dt = 100 A/µs,		295.7		nC
I _{RRM}	Reverse recovery current	V _{DD} = 80 V, T _j = 150 °C		7.1		Α

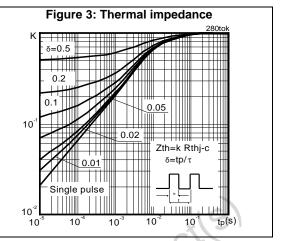
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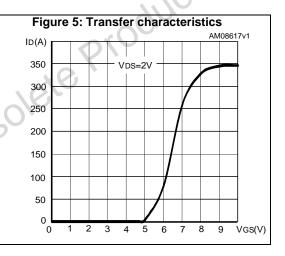


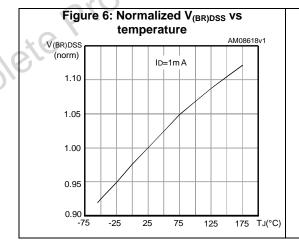
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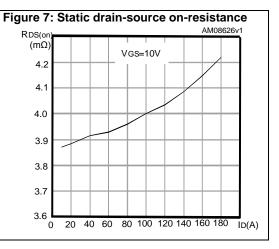
2.1 Electrical characteristics (curves)







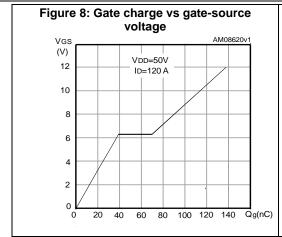




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STH180N10F3-6 Electrical characteristics



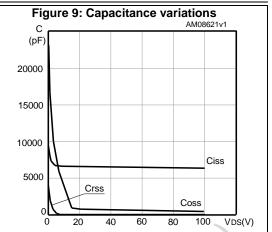
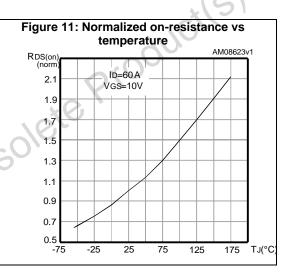
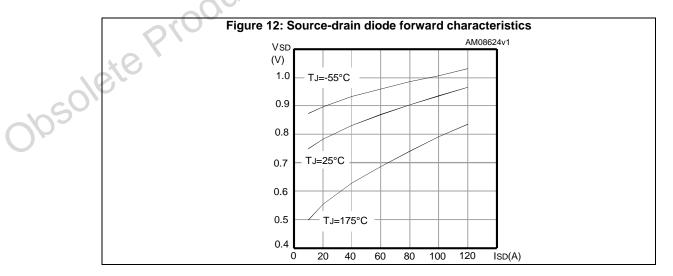


Figure 10: Normalized gate threshold voltage vs temperature VGS(th (norm) ID=250μ A 1.3 1.1 0.9 0.7 0.5 0.3 -25 25 75 175 125 TJ(°C)

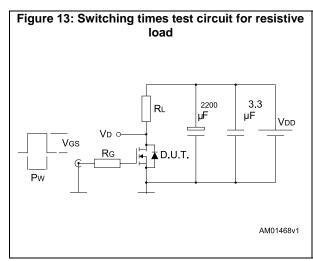


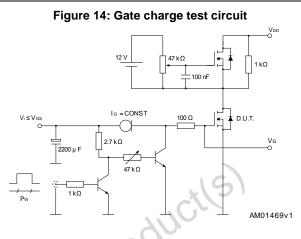


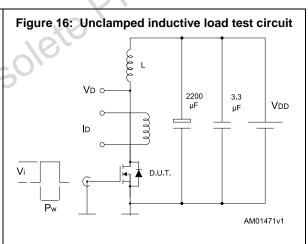


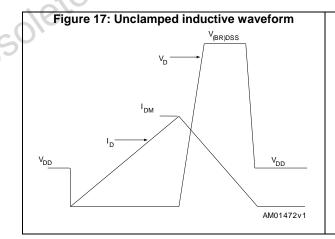
Test circuits STH180N10F3-6

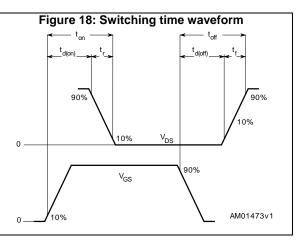
3 Test circuits











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STH180N10F3-6 Package information

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

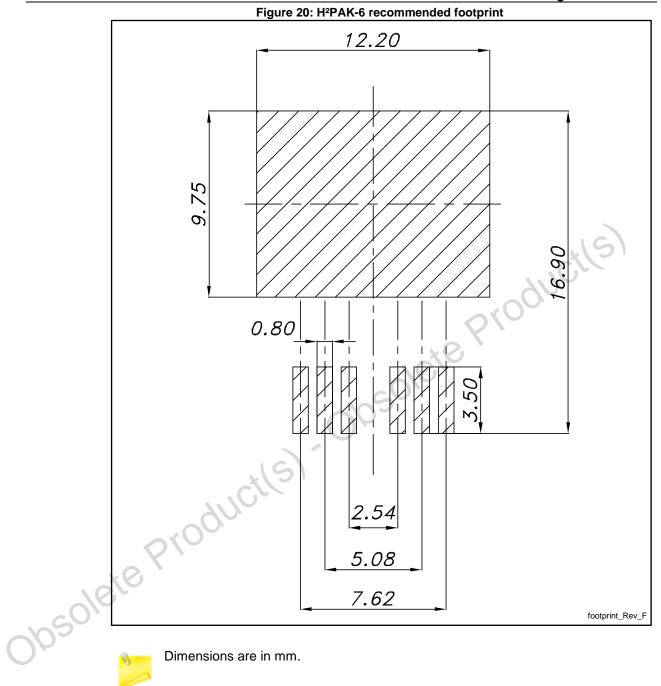
4.1 H²PAK-6 package information

Figure 19: H²PAK-6 outline)osolete Prod 0.25 Gauge Plane 8159693_Rev_F

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Table 8: H²PAK-6 mechanical data

	Table 8: HPAK-6	mechanical data		
Dim.	mm			
Dilli.	Min.	Тур.	Max.	
А	4.30		4.80	
A1	0.03		0.20	
С	1.17		1.37	
е	2.34		2.74	
e1	4.88		5.28	
e2	7.42		7.82	
Е	0.45		0.60	
F	0.50		0.70	
Н	10.00		10.40	
H1	7.40	_	7.80	
L	14.75		15.25	
L1	1.27	e (1.40	
L2	4.35	01	4.95	
L3	6.85	oletePi	7.25	
L4	1.5	10,10	1.75	
M	1.90	0/0	2.50	
R	0.20	0	0.60	
V	0°		8°	
ete Produ	cile			



Package information STH180N10F3-6

Packing information 4.2

Figure 21: Tape outline

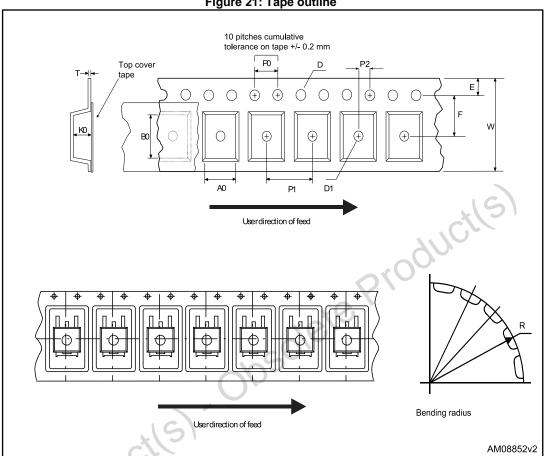
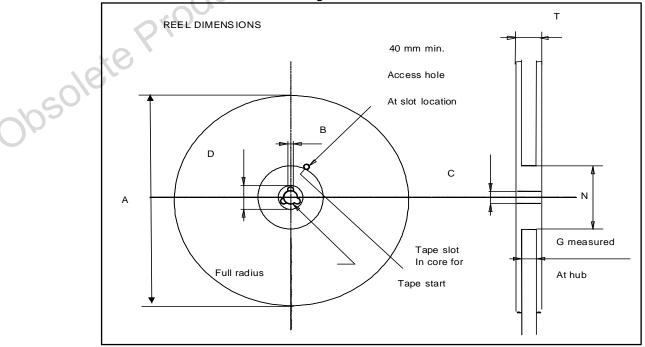


Figure 22: Reel outline



12/15 DocID022347 Rev 4 Table 9: Tape and reel mechanical data

	Tape 3. Tape and		Reel			
	Dim	mm		Dim.	mm	
	Dim.	Min.	Min. Max.		Min. M	
	A0	10.5	10.7	А		330
	В0	15.7	15.9	В	1.5	
	D	1.5	1.6	С	12.8	13.2
	D1	1.59	1.61	D	20.2	
	E	1.65	1.85	G	24.4	26.4
	F	11.4	11.6	N	100	
	K0	4.8	5.0	Т		30.4
	P0	3.9	4.1			115
	P1	11.9	12.1	Base o	luantity	1000
	P2	1.9	2.1	Bulk q	uantity	1000
	R	50			100	
	Т	0.25	0.35	•	010	
	W	23.7	24.3			
			Ok	50		
)10501	ste Pro	ducil	24.3	50		

Revision history STH180N10F3-6

5 Revision history

Table 10: Document revision history

	Date	Revision	Changes
	10-Oct-2011	1	First version
	04-Nov-2011	2	Updated features in cover page
	14-Nov-2014	3	 Updated: H²PAK-6 package mechanical data. Updated: title, features and description. Minor text changes.
	26-Nov-2014	4	Updated Table 4: "On/off-state".
Obsole	ie Pro	ducti	Updated Table 4: "On/off-state".

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